

D12 and from the surface processing apparatus; and one or more processing apparatuses capable of transporting the object to be processed to and from the transport chamber.

Please substitute the following paragraph for the paragraph located at page 6, lines 10-12:

D13 The invention is characterized in that the processing apparatus is a metal wiring formation chamber for making metal wiring on the object to be processed.

**IN THE CLAIMS:**

Please cancel claims 14-20, and 29-32, and amend claims 24, 25, and 27 to read as follows:

D14 <sup>6</sup>24. An apparatus for surface treatment according to claim <sup>5</sup>23, wherein the means for promoting adhesion of the ClF<sub>3</sub> gas to the object to be processed is provided in the mount, the means for promoting adhesion thereby cooling the object to be processed on the mount.

<sup>7</sup>25. An apparatus for surface treatment according to claim <sup>6</sup>24, wherein the means for activating the ClF<sub>3</sub> gas heats the object to be processed in a heating position at a distance from an object setting position of the object on the mount.

D15 <sup>2</sup>27. A cluster device comprising: the apparatus for surface treatment according to claim <sup>1</sup>21, further comprising:

a transport chamber for maintaining a non-reactive atmosphere therein and for transporting an object to be processed in the non-reactive atmosphere to and from the apparatus for surface treatment; and